2STA2121

High power PNP epitaxial planar bipolar transistor

Preliminary data

Features

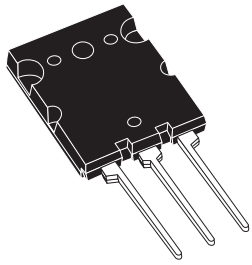
- High breakdown voltage V_{CEO} = 250 V
- Complementary to 2STC5949
- Fast-switching speed
- Typical f_t = 25 MHz
- Fully characterized at 125 °C

Applications

- Audio power amplifier

Description

The device is a PNP transistor manufactured using new BiT-LA (Bipolar transistor for linear amplifier) technology. The resulting transistor shows good gain linearity behaviour.



TO-264

Figure 1. Internal schematic diagram

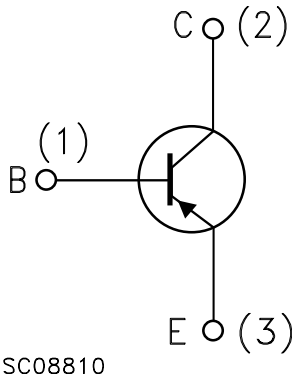


Table 1. Device summary

Order code	Marking	Package	Packaging
2STA2121	2STA2121	TO-264	Tube

1 Electrical ratings

Table 2. Absolute maximum rating

Symbol	Parameter	Value	Unit
V_{CBO}	Collector-emitter voltage (I_E = 0)	-250	V
V_{CEO}	Collector-emitter voltage (I_B = 0)	-250	V
V_{EBO}	Collector-base voltage (I_C = 0)	-6	V
I_C	Collector current	-17	A
I_{CM}	Collector peak current (t_P < 5ms)	-34	A
P_{TOT}	Total dissipation at T_c = 25°C	220	W
T_{stg}	Storage temperature	-65 to 150	°C
T_J	Max. operating junction temperature	150	°C

Table 3. Thermal data

Symbol	Parameter		Value	Unit
$R_{thj\text{-}case}$	Thermal resistance junction-case	max	0.568	°C/W

2 Electrical characteristics

(T_{case} = 25°C; unless otherwise specified)

Table 4. Electrical characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{CBO}	Collector cut-off current (I_E = 0)	V_{CB} = -250 V			-5	µA
I_{EBO}	Emitter cut-off current (I_C = 0)	V_{EB} = -6 V			-5	µA
$V_{(BR)CEO}$(1)	Collector-emitter breakdown voltage (I_B = 0)	I_C = -50 mA	-250			V
$V_{(BR)CBO}$	Collector-emitter breakdown voltage (I_E = 0)	I_C = -100 µA	-250			V
$V_{(BR)EBO}$(1)	Collector-emitter breakdown voltage (I_C = 0)	I_E = -1 mA	-6			V
$V_{CE(sat)}$ (1)	Collector-emitter saturation voltage	I_C = -8 A I_B = -800 mA			-3	V
V_{BE} (1)	Base-emitter saturation voltage	I_C = -7 A V_{CE} = -5 V			-1.5	V
h_{FE}	DC current gain	I_C = -1 A V_{CE} = -5V I_C = -7 A V_{CE} = -5 V	80 35		160	
f_T	Transition frequency	I_C = -1 A V_{CE} = -5 V		25		MHz

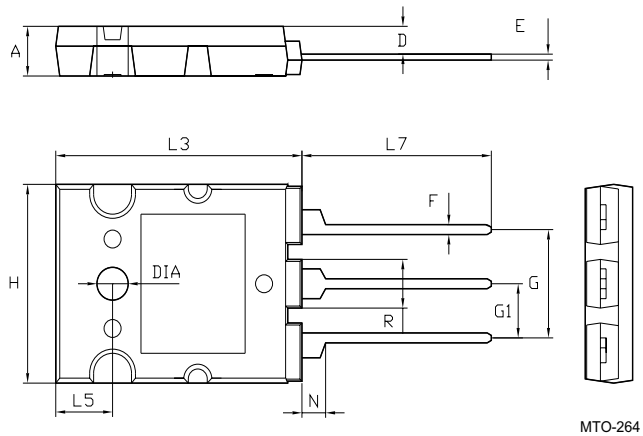
1. Pulsed duration = 300 µs, duty cycle ≤1.5%

3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

TO-264 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.80		5.20	0.189		0.205
D	2.50		3.10	0.098		0.122
E	0.50	0.60	0.85	0.020	0.24	0.033
F	0.90	1.00	1.25	0.036	0.039	0.049
G	10.30		11.50	0.406		0.453
G1		5.45			0.215	
H	19.80		20.20	0.780		0.795
L3	25.80		26.20	1.016		1.031
L5	5.80		6.20	0.228		0.244
L7	19.50		20.50	0.768		0.807
N	2.30		2.70	0.091		0.106
R	4.7		5.10	0.185		0.201
DIA	3.10		3.50	0.122		0.138



MTO-264 rev.1

4 Revision history

Table 5. Document revision history

Date	Revision	Changes
23-Nov-2007	1	Initial release

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